



# STPS40150CG/CT/CW

## HIGH VOLTAGE POWER SCHOTTKY RECTIFIER

### MAJOR PRODUCTS CHARACTERISTICS

I <sub>F(AV)</sub>	2 x 20 A
V <sub>RRM</sub>	150 V
T <sub>j</sub> (max)	175°C
V <sub>F</sub> (max)	0.75 V

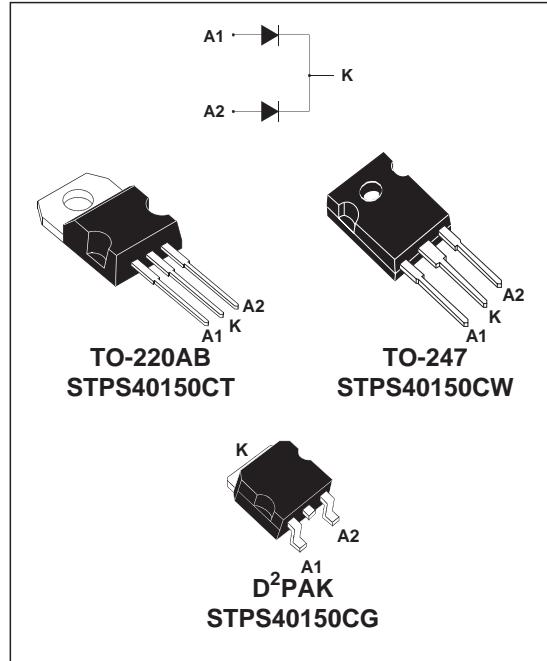
### FEATURES AND BENEFITS

- HIGH JUNCTION TEMPERATURE CAPABILITY
- LOW LEAKAGE CURRENT
- GOOD TRADE OFF BETWEEN LEAKAGE CURRENT AND FORWARD VOLTAGE DROP
- LOW THERMAL RESISTANCE
- HIGH FREQUENCY OPERATION

### DESCRIPTION

Dual center tap Schottky rectifiers suited for high frequency switch mode power supply.

Packaged in TO-247, TO-220AB and D<sup>2</sup>PAK, this devices is intended for use to enhance the reliability of the application.



### ABSOLUTE RATINGS (limiting values, per diode)

Symbol	Parameter			Value	Unit
V <sub>RRM</sub>	Repetitive peak reverse voltage			150	V
I <sub>F(RMS)</sub>	RMS forward current			60	A
I <sub>F(AV)</sub>	Average forward current	T <sub>c</sub> = 150°C δ = 0.5	Per diode Per device	20 40	A
I <sub>FSM</sub>	Surge non repetitive forward current	tp = 10 ms Sinusoidal		250	A
P <sub>ARM</sub>	Repetitive peak avalanche power	tp = 1μs T <sub>j</sub> = 25°C		14100	W
T <sub>stg</sub>	Storage temperature range			- 65 to + 175	°C
T <sub>j</sub>	Maximum operating junction temperature *			175	°C
dV/dt	Critical rate of rise of reverse voltage			10000	V/μs

\* :  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th}(j - a)}$  thermal runaway condition for a diode on its own heatsink

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### THERMAL RESISTANCES

Symbol	Parameter			Value	Unit
R <sub>th(j-c)</sub>	Junction to case	TO-220AB / D <sup>2</sup> PAK	Per diode Total	1.2 0.85	°C/W
R <sub>th(j-c)</sub>	Junction to case	TO-247	Per diode Total	1.2 0.85	°C/W
R <sub>th(c)</sub>	Coupling			0.5	°C/W

When the diodes 1 and 2 are used simultaneously :  
 $\Delta T_j(\text{diode 1}) = P(\text{diode 1}) \times R_{\text{th(j-c)}}(\text{Per diode}) + P(\text{diode 2}) \times R_{\text{th(c)}}$

### STATIC ELECTRICAL CHARACTERISTICS (per diode)

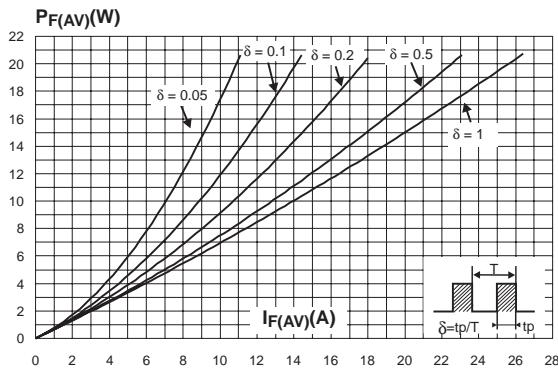
Symbol	Parameter	Tests Conditions		Min.	Typ.	Max.	Unit
I <sub>R</sub> *	Reverse leakage current	T <sub>j</sub> = 25°C	V <sub>R</sub> = V <sub>RRM</sub>		2	8	μA
		T <sub>j</sub> = 125°C			2	11	mA
V <sub>F</sub> *	Forward voltage drop	T <sub>j</sub> = 25°C	I <sub>F</sub> = 20 A			0.92	V
		T <sub>j</sub> = 125°C	I <sub>F</sub> = 20 A		0.69	0.75	
		T <sub>j</sub> = 25°C	I <sub>F</sub> = 40 A			1.00	
		T <sub>j</sub> = 125°C	I <sub>F</sub> = 40 A		0.79	0.86	

Pulse test : \* tp = 380 μs, δ < 2%

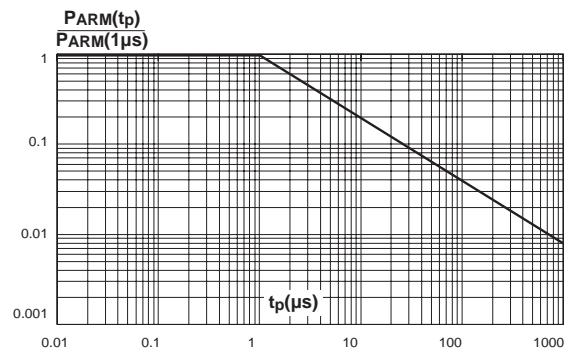
To evaluate the conduction losses use the following equation :

$$P = 0.64 \times I_{F(AV)} + 0.0055 I_F^2 (\text{RMS})$$

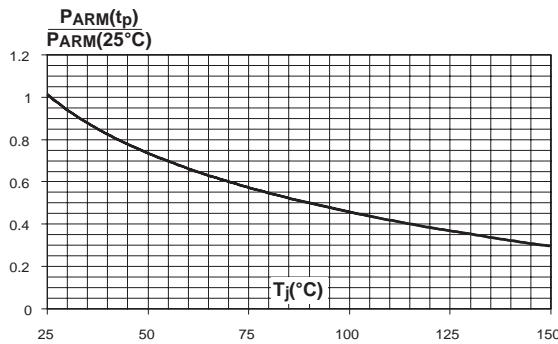
**Fig. 1:** Conduction losses versus average current (per diode).



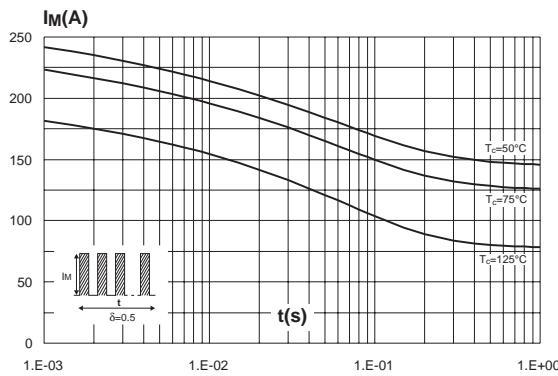
**Fig. 2:** Normalized avalanche power derating versus pulse duration.



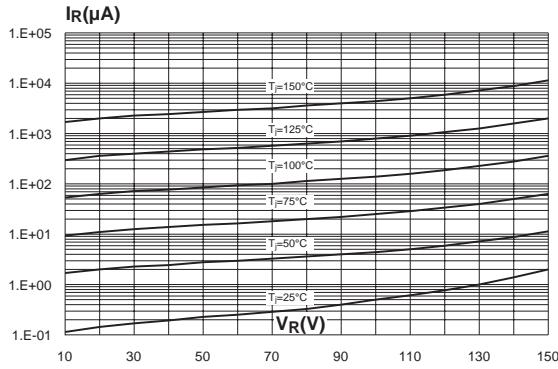
**Fig. 3:** Normalized avalanche power derating versus junction temperature.



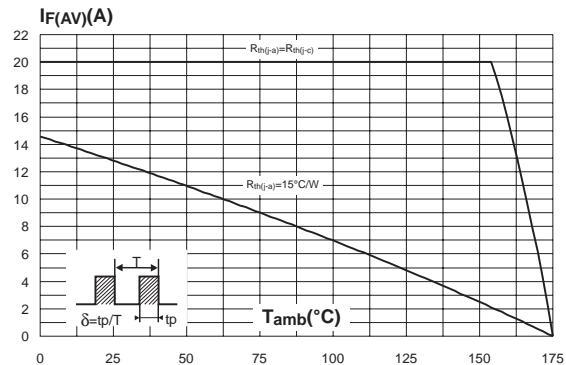
**Fig. 5:** Non repetitive surge peak forward current versus overload duration (maximum values, per diode).



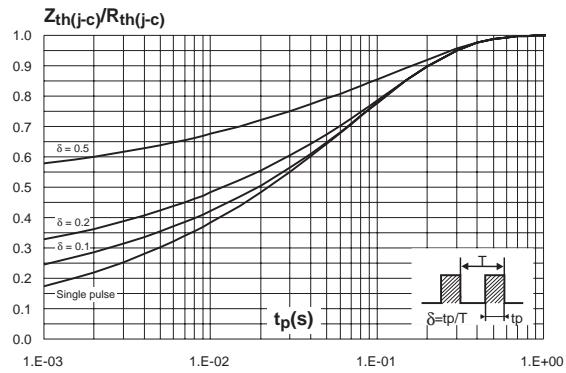
**Fig. 7:** Reverse leakage current versus reverse voltage applied (typical values, per diode).



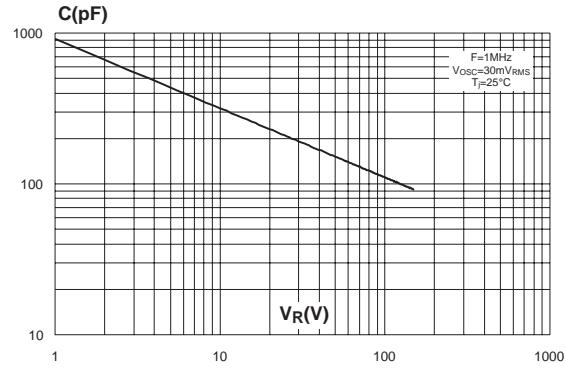
**Fig. 4:** Average forward current versus ambient temperature ( $\delta=0.5$ , per diode).



**Fig. 6:** Relative variation of thermal impedance junction to case versus pulse duration.

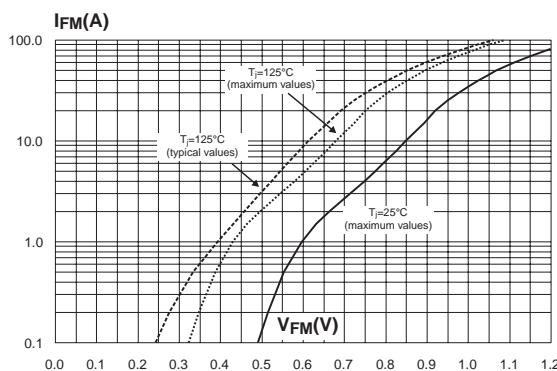


**Fig. 8:** Junction capacitance versus reverse voltage applied (typical values, per diode).

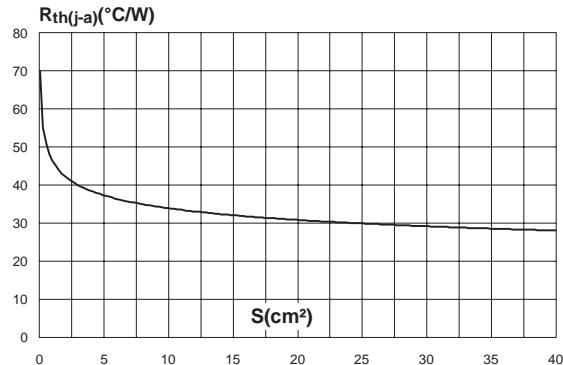


## STPS40150CT/CW/CG

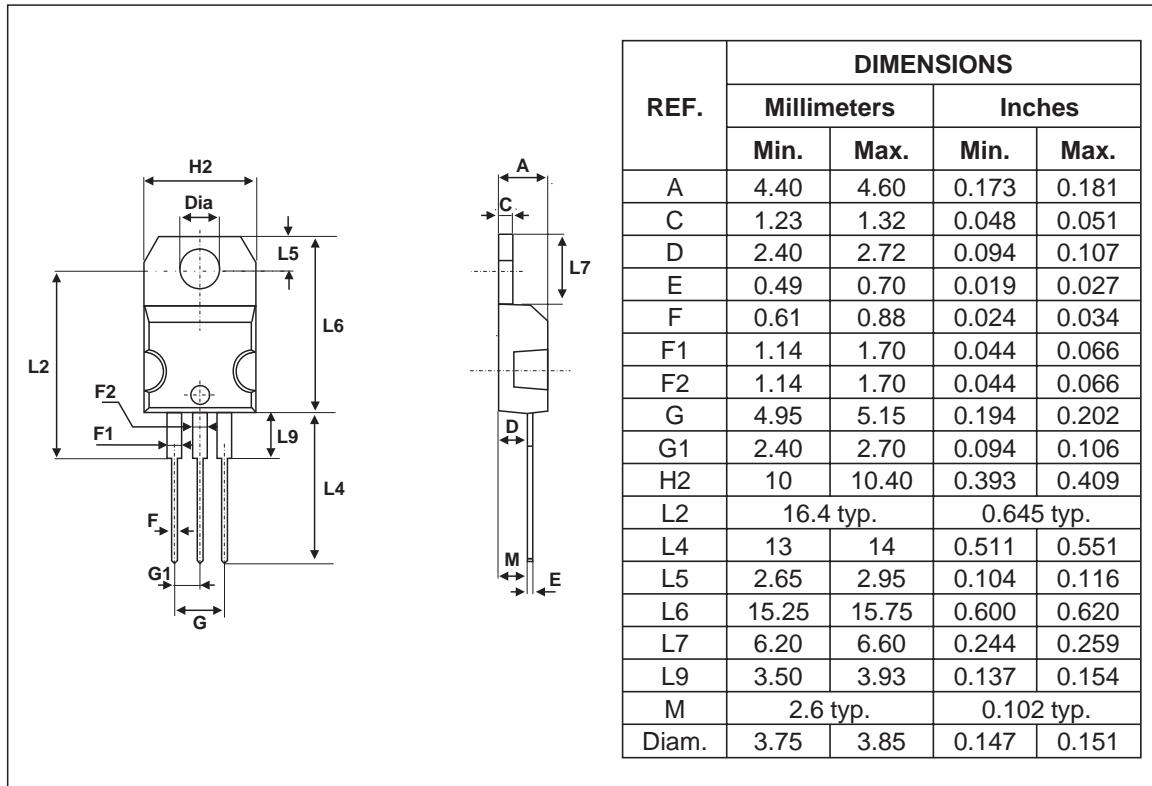
**Fig. 9:** Forward voltage drop versus forward current (per diode).



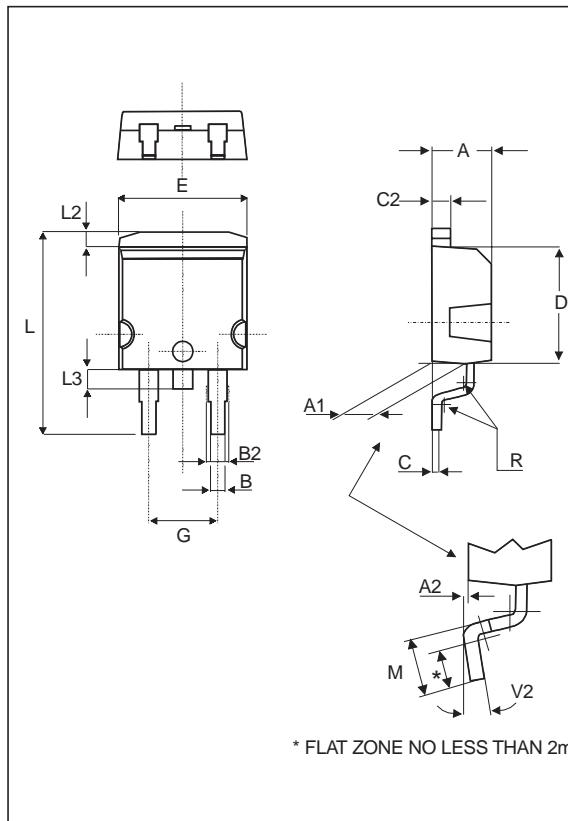
**Fig. 10:** Thermal resistance junction to ambient versus copper surface under tab (epoxy printed board FR4, Cu=35µm) (D<sup>2</sup>PAK).



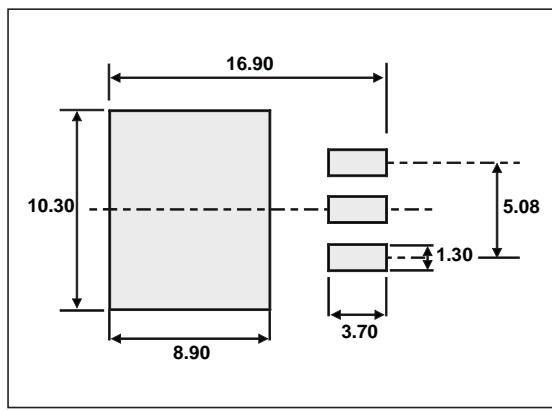
## PACKAGE MECHANICAL DATA TO-220AB



- Cooling method : C
- Recommended torque value : 0.55 m.N
- Maximum torque value : 0.70 m.N

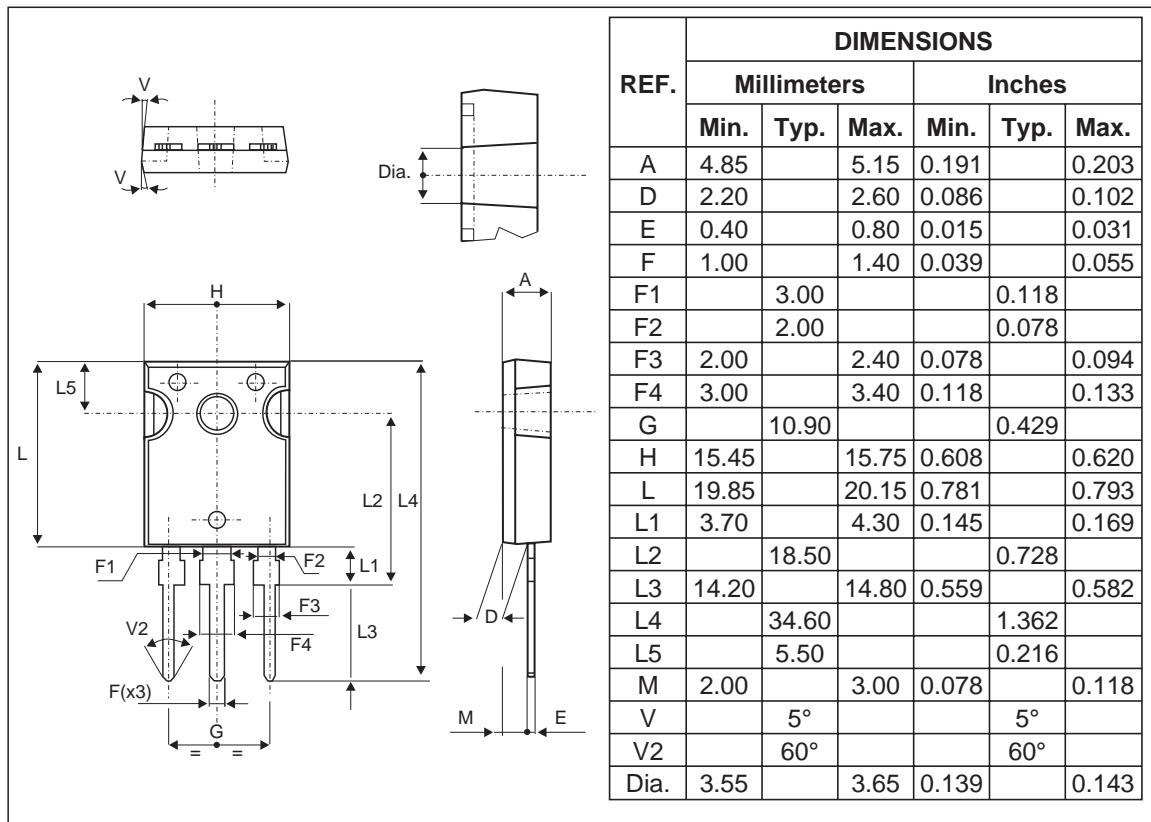
**PACKAGE MECHANICAL DATA**  
**D<sup>2</sup>PAK**


REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.49	2.69	0.098	0.106
A2	0.03	0.23	0.001	0.009
B	0.70	0.93	0.027	0.037
B2	1.14	1.70	0.045	0.067
C	0.45	0.60	0.017	0.024
C2	1.23	1.36	0.048	0.054
D	8.95	9.35	0.352	0.368
E	10.00	10.40	0.393	0.409
G	4.88	5.28	0.192	0.208
L	15.00	15.85	0.590	0.624
L2	1.27	1.40	0.050	0.055
L3	1.40	1.75	0.055	0.069
M	2.40	3.20	0.094	0.126
R	0.40 typ.		0.016 typ.	
V2	0°	8°	0°	8°

**FOOT PRINT DIMENSIONS** (in millimeters)


## STPS40150CT/CW/CG

### PACKAGE MECHANICAL DATA TO-247



- Cooling method : C
- Recommended torque value : 0.8m.N
- Maximum torque value : 1.0m.N

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS40150CT	STPS40150CT	TO-220AB	2g	50	Tube
STPS40150CW	STPS40150CW	TO-247	4.4g	30	Tube
STPS40150CG	STPS40150CG	D <sup>2</sup> PAK	1.48g	50	Tube
STPS40150CG-TR	STPS40150CG-TR	D <sup>2</sup> PAK	1.48g	1000	Tape & reel

- Epoxy meets UL94,V0

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